CLAIMS:

1. – 14. (cancelled)

15. (Currently amended) A method for manufacturing an assembly including a printed circuit board and a plurality of tape carrier packages attached to the printed circuit board, each of the tape carrier packages having conductive leads parallel with each other, the method comprising:

arranging the tape carrier packages along a common axis such that center lines of the tape carrier packages, which are substantially perpendicular to the common axis, wherein the central lines of the tape carrier package adjacent to each other are spaced apart from each other at respective first intervals;

forming a plurality of land groups on the printed circuit board, the land groups comprising conductive leads respectively and being arranged along the common axis, center lines of the land groups, which are substantially perpendicular to the common axis, being spaced apart from each adjacent other at respective second intervals determined in accordance with thermal expansion properties of the printed circuit board such that, in a pre-compression bonded state, the respective second intervals are smaller than the respective first intervals;

thermocompression bonding the tape carrier packages to the printed circuit board; and,

during the thermocompression bonding, allowing the printed circuit board to expand such that the respective lands are substantially aligned with corresponding ones of the leads of the tape carrier packages.

16. (cancelled)

17. (Previously presented) The method of claim 15, further comprising measuring the thermal expansion properties of the printed circuit board before forming the lands thereon.

18. (Previously presented) The method of claim 15, wherein the respective second intervals between adjacent ones of the land groups are asymmetric with respect to a line passing through the middle of a width of the printed circuit board when the printed circuit board is asymmetric with respect to said line.

19. (Currently amended) A printed circuit board capable of being adapted to be electrically connected to an external device through a plurality of tape carrier packages, each of the tape carrier packages having a conductive lead group which includes a plurality of conductive leads, the tape carrier packages being arranged such that center lines of the conductive lead groups of the tape carrier packages are spaced from each adjacent other at first intervals, the printed circuit board comprising:

a substrate; and,

a plurality of conductive land groups formed on the substrate and disposed parallel to and spaced apart from each other such that center lines of the land groups are spaced apart from each adjacent other at second intervals, respective one of the plurality of conductive land groups corresponding to a respective one of the conductive lead groups of the tape carrier packages, wherein the second intervals are respectively smaller than the first intervals.

20. (canceled)

21. (Previously presented) The printed circuit board of claim 19, wherein the second intervals respectively become substantially the same as the first intervals by thermal expansion when the printed circuit board undergoes a thermo-compression bonding process.

22. (Currently amended) The printed circuit board of claim 19, wherein the second intervals are asymmetric with respect to a line passing through a midpoint of a width of the printed circuit board when the printed circuit board is asymmetric with respect to said line.

23. (Currently amended) A method of manufacturing a printed circuit board ~~that is to be~~ capable of being electrically connected to an external device through a plurality of tape carrier packages spaced apart from each other, comprising:

forming land groups that correspond one-to-one with each of the tape carrier packages on a substrate such that intervals between center lines of the land groups are respectively smaller than intervals between center lines of the tape carrier packages.

24. (Previously presented) The method of claim 23, wherein the interval between the printed circuit board land groups determined by:

measuring an amount of total thermal expansion of the substrate under a thermo-compression bonding process, and

obtaining the interval between the printed circuit board land groups by considering the amount of total thermal expansion.

25. (canceled)